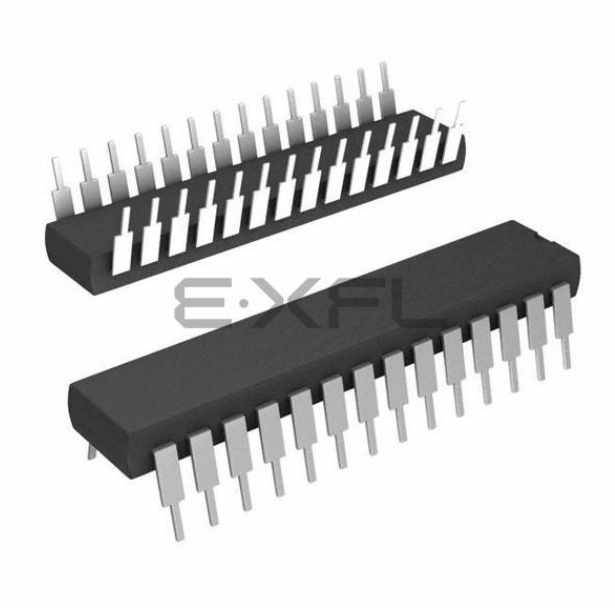


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv16ka302-e-sp

The internal oscillator block also provides a stable reference source for the Fail-Safe Clock Monitor (FSCM). This option constantly monitors the main clock source against a reference signal provided by the internal oscillator and enables the controller to switch to the internal oscillator, allowing for continued low-speed operation or a safe application shutdown.

1.1.4 EASY MIGRATION

Regardless of the memory size, all the devices share the same rich set of peripherals, allowing for a smooth migration path as applications grow and evolve.

The consistent pinout scheme used throughout the entire family also helps in migrating to the next larger device. This is true when moving between devices with the same pin count, or even jumping from 20-pin or 28-pin devices to 44-pin/48-pin devices.

The PIC24F family is pin compatible with devices in the dsPIC33 family, and shares some compatibility with the pinout schema for PIC18 and dsPIC30. This extends the ability of applications to grow from the relatively simple, to the powerful and complex.

1.2 Other Special Features

- **Communications:** The PIC24FV32KA304 family incorporates a range of serial communication peripherals to handle a range of application requirements. There is an I^2C™ module that supports both the Master and Slave modes of operation. It also comprises UARTs with built-in IrDA® encoders/decoders and an SPI module.
- **Real-Time Clock/Calendar:** This module implements a full-featured clock and calendar with alarm functions in hardware, freeing up timer resources and program memory space for use of the core application.
- **12-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, and faster sampling speed. The 16-deep result buffer can be used either in Sleep to reduce power, or in Active mode to improve throughput.
- **Charge Time Measurement Unit (CTMU) Interface:** The PIC24FV32KA304 family includes the new CTMU interface module, which can be used for capacitive touch sensing, proximity sensing, and also for precision time measurement and pulse generation.

1.3 Details on Individual Family Members

Devices in the PIC24FV32KA304 family are available in 20-pin, 28-pin, 44-pin and 48-pin packages. The general block diagram for all devices is shown in Figure 1-1.

The devices are different from each other in four ways:

1. Flash program memory (16 Kbytes for PIC24FV16KA devices, 32 Kbytes for PIC24FV32KA devices).
2. Available I/O pins and ports (18 pins on two ports for 20-pin devices, 22 pins on two ports for 28-pin devices and 38 pins on three ports for 44/48-pin devices).
3. Alternate SCLx and SDAx pins are available only in 28-pin, 44-pin and 48-pin devices and not in 20-pin devices.
4. Members of the PIC24FV32KA301 family are available as both standard and high-voltage devices. High-voltage devices, designated with an “FV” in the part number (such as PIC24FV32KA304), accommodate an operating V_{DD} range of 2.0V to 5.5V, and have an on-board Voltage Regulator that powers the core. Peripherals operate at V_{DD}. Standard devices, designated by “F” (such as PIC24F32KA304), function over a lower V_{DD} range of 1.8V to 3.6V. These parts do not have an internal regulator, and both the core and peripherals operate directly from V_{DD}.

All other features for devices in this family are identical; these are summarized in Table 1-1.

A list of the pin features available on the PIC24FV32KA304 family devices, sorted by function, is provided in Table 1-3.

Note:	Table 1-1 provides the pin location of individual peripheral features and not how they are multiplexed on the same pin. This information is provided in the pinout diagrams on pages 3, 4, 5, 6 and 7 of the data sheet. Multiplexed features are sorted by the priority given to a feature, with the highest priority peripheral being listed first.

4.2.5 SOFTWARE STACK

In addition to its use as a working register, the W15 register in PIC24F devices is also used as a Software Stack Pointer. The pointer always points to the first available free word and grows from lower to higher addresses. It predecrements for stack pops and post-increments for stack pushes, as shown in Figure 4-4.

Note that for a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, ensuring that the MSB is always clear.

Note:	A PC push during exception processing will concatenate the SRL register to the MSB of the PC prior to the push.

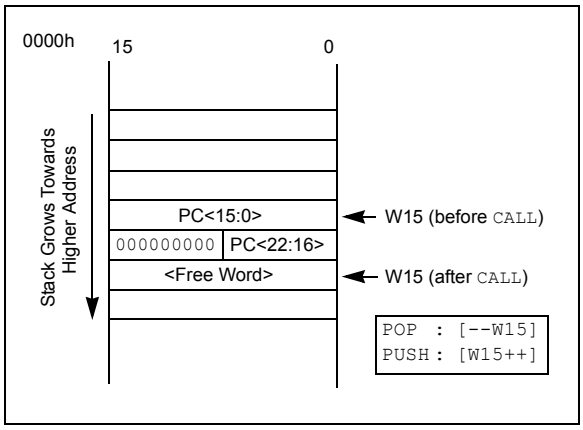
The Stack Pointer Limit Value (SPLIM) register, associated with the Stack Pointer, sets an upper address boundary for the stack. SPLIM is uninitialized at Reset. As is the case for the Stack Pointer, SPLIM<0> is forced to '0' as all stack operations must be word-aligned. Whenever an EA is generated, using W15 as a source or destination pointer, the resulting address is compared with the value in SPLIM. If the contents of the Stack Pointer (W15) and the SPLIM register are equal, and a push operation is performed, a stack error trap will not occur. The stack error trap will occur on a subsequent push operation.

Thus, for example, if it is desirable to cause a stack error trap when the stack grows beyond address, 0DF6 in RAM, initialize the SPLIM with the value, 0DF4.

Similarly, a Stack Pointer underflow (stack error) trap is generated when the Stack Pointer address is found to be less than 0800h. This prevents the stack from interfering with the Special Function Register (SFR) space.

Note:	A write to the SPLIM register should not be immediately followed by an indirect read operation using W15.

FIGURE 4-4: CALL STACK FRAME



4.3 Interfacing Program and Data Memory Spaces

The PIC24F architecture uses a 24-bit wide program space and 16-bit wide data space. The architecture is also a modified Harvard scheme, meaning that data can also be present in the program space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Apart from the normal execution, the PIC24F architecture provides two methods by which the program space can be accessed during operation:

- Using table instructions to access individual bytes or words anywhere in the program space
- Remapping a portion of the program space into the data space, PSV

Table instructions allow an application to read or write small areas of the program memory. This makes the method ideal for accessing data tables that need to be updated from time to time. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for look-ups from a large table of static data. It can only access the least significant word (lsw) of the program word.

4.3.1 ADDRESSING PROGRAM SPACE

Since the address ranges for the data and program spaces are 16 and 24 bits, respectively, a method is needed to create a 23-bit or 24-bit program address from 16-bit data registers. The solution depends on the interface method to be used.

For table operations, the 8-bit Table Memory Page Address register (TBLPAG) is used to define a 32K word region within the program space. This is concatenated with a 16-bit EA to arrive at a full 24-bit program space address. In this format, the Most Significant bit (MSb) of TBLPAG is used to determine if the operation occurs in the user memory (TBLPAG<7> = 0) or the configuration memory (TBLPAG<7> = 1).

For remapping operations, the 8-bit Program Space Visibility Page Address register (PSVPAG) is used to define a 16K word page in the program space. When the MSb of the EA is '1', PSVPAG is concatenated with the lower 15 bits of the EA to form a 23-bit program space address. Unlike the table operations, this limits remapping operations strictly to the user memory area.

Table 4-27 and Figure 4-5 show how the program EA is created for table operations and remapping accesses from the data EA. Here, the P<23:0> bits refer to a program space word, whereas the D<15:0> bits refer to a data space word.

5.0 FLASH PROGRAM MEMORY

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Flash programming, refer to the *"PIC24F Family Reference Manual"*, **Section 4. "Program Memory"** (DS39715).

The PIC24FV32KA304 family of devices contains internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable when operating with VDD over 1.8V.

Flash memory can be programmed in three ways:

- In-Circuit Serial Programming™ (ICSP™)
- Run-Time Self Programming (RTSP)
- Enhanced In-Circuit Serial Programming (Enhanced ICSP)

ICSP allows a PIC24FV32KA304 device to be serially programmed while in the end application circuit. This is simply done with two lines for the programming clock and programming data (which are named PGECx and PGEDx, respectively), and three other lines for power (VDD), ground (VSS) and Master Clear/Program mode Entry Voltage ($\overline{MCLR}$/VPP). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or custom firmware to be programmed.

Run-Time Self Programming (RTSP) is accomplished using TBLRD (Table Read) and TBLWT (Table Write) instructions. With RTSP, the user may write program memory data in blocks of 32 instructions (96 bytes) at a time, and erase program memory in blocks of 32, 64 and 128 instructions (96,192 and 384 bytes) at a time.

The NVMOP<1:0> (NVMCON<1:0>) bits decide the erase block size.

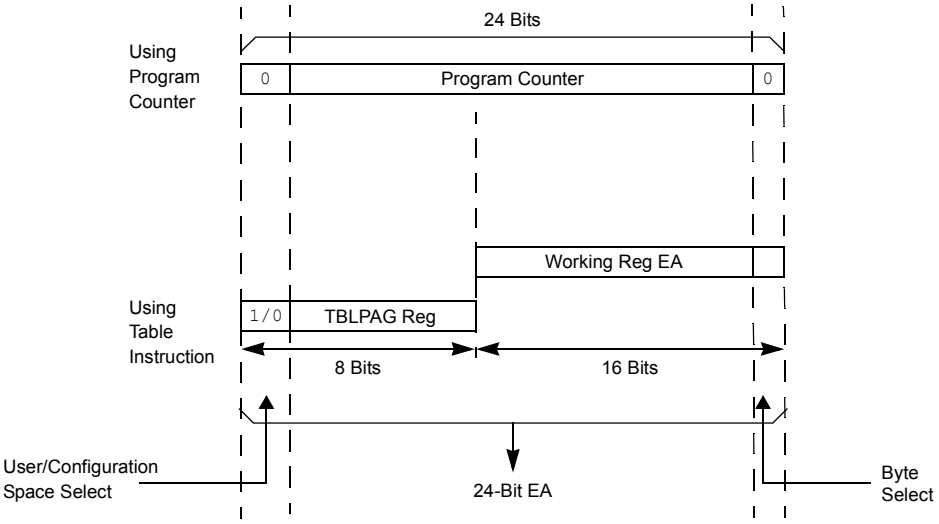
5.1 Table Instructions and Flash Programming

Regardless of the method used, Flash memory programming is done with the table read and write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using the TBLPAG<7:0> bits and the Effective Address (EA) from a W register, specified in the table instruction, as depicted in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



EXAMPLE 5-2: ERASING A PROGRAM MEMORY ROW – 'C' LANGUAGE CODE

```
// C example using MPLAB C30

    int __attribute__ ((space(auto_psv))) progAddr = 0x1234;// Global variable located in Pgm Memory
    unsigned int offset;

//Set up pointer to the first memory location to be written

    TBLPAG = __builtin_tblpage(&progAddr);              // Initialize PM Page Boundary SFR
    offset = __builtin_tbloffset(&progAddr);            // Initialize lower word of address

    __builtin_tblwtl(offset, 0x0000);                   // Set base address of erase block
                                                        // with dummy latch write

    NVMCON = 0x4058;                                    // Initialize NVMCON

    asm("DISI #5");                                     // Block all interrupts for next 5
                                                        // instructions
    __builtin_write_NVM();                              // C30 function to perform unlock
                                                        // sequence and set WR
```

EXAMPLE 5-3: LOADING THE WRITE BUFFERS – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row programming operations
       MOV     #0x4004, W0                  ;
       MOV     W0, NVMCON                   ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0                  ;
       MOV     W0, TBLPAG                   ; Initialize PM Page Boundary SFR
       MOV     #0x6000, W0                  ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2              ;
       MOV     #HIGH_BYTE_0, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2              ;
       MOV     #HIGH_BYTE_1, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2              ;
       MOV     #HIGH_BYTE_2, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
       •
       •
       •
; 32nd_program_word
       MOV     #LOW_WORD_31, W2             ;
       MOV     #HIGH_BYTE_31, W3            ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0]                     ; Write PM high byte into program latch
```

REGISTER 6-1: NVMCON: NONVOLATILE MEMORY CONTROL REGISTER

R/S-0, HC	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	PGMONLY	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ERASE	NVMOP5	NVMOP4	NVMOP3	NVMOP2	NVMOP1	NVMOP0
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	S = Settable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit (program or erase)
1 = Initiates a data EEPROM erase or write cycle (can be set, but not cleared in software)
0 = Write cycle is complete (cleared automatically by hardware)

bit 14 **WREN:** Write Enable bit (erase or program)
1 = Enables an erase or program operation
0 = No operation allowed (device clears this bit on completion of the write/erase operation)

bit 13 **WRERR:** Write Flash Error Flag bit
1 = A write operation is prematurely terminated (any $\overline{\text{MCLR}}$ or WDT Reset during programming operation)
0 = The write operation completed successfully

bit 12 **PGMONLY:** Program Only Enable bit
1 = Write operation is executed without erasing target address(es) first
0 = Automatic erase-before-write
Write operations are preceded automatically by an erase of the target address(es).

bit 11-7 **Unimplemented:** Read as '0'

bit 6 **ERASE:** Erase Operation Select bit
1 = Performs an erase operation when WR is set
0 = Performs a write operation when WR is set

bit 5-0 **NVMOP<5:0>:** Programming Operation Command Byte bits
Erase Operations (when ERASE bit is '1'):
011010 = Erases 8 words
011001 = Erases 4 words
011000 = Erases 1 word
0100xx = Erases entire data EEPROM
Programming Operations (when ERASE bit is '0'):
0010xx = Writes 1 word

REGISTER 8-11: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0

bit 1 **IC1IE:** Input Capture Channel 1 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **INT0IE:** External Interrupt 0 Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 8-29: IPC16: INTERRUPT PRIORITY CONTROL REGISTER 16

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	CRCIP2	CRCIP1	CRCIP0	—	U2ERIP2	U2ERIP1	U2ERIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	U1ERIP2	U1ERIP1	U1ERIP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **CRCIP<2:0>:** CRC Generator Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **U2ERIP<2:0>:** UART2 Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **U1ERIP<2:0>:** UART1 Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

9.1 CPU Clocking Scheme

The system clock source can be provided by one of four sources:

- Primary Oscillator (POSC) on the OSCI and OSCO pins
- Secondary Oscillator (SOSC) on the SOSCI and SOSCO pins

  The PIC24FV32KA304 family devices consist of two types of secondary oscillator:

  - High-Power Secondary Oscillator
  - Low-Power Secondary Oscillator

  These can be selected by using the SOSCSEL (FOSC<5>) bit.
- Fast Internal RC (FRC) Oscillator
  - 8 MHz FRC Oscillator
  - 500 kHz Lower Power FRC Oscillator
- Low-Power Internal RC (LPRC) Oscillator with two modes:
  - High-Power/High Accuracy mode
  - Low-Power/Low Accuracy mode

The primary oscillator and 8 MHz FRC sources have the option of using the internal 4x PLL. The frequency of the FRC clock source can optionally be reduced by the programmable clock divider. The selected clock source generates the processor and peripheral clock sources.

The processor clock source is divided by two to produce the internal instruction cycle clock, FCY. In this document, the instruction cycle clock is also denoted by FOSC/2. The internal instruction cycle clock, FOSC/2, can be provided on the OSCO I/O pin for some operating modes of the primary oscillator.

9.2 Initial Configuration on POR

The oscillator source (and operating mode) that is used at a device Power-on Reset (POR) event is selected using Configuration bit settings. The Oscillator Configuration bit settings are located in the Configuration registers in the program memory (for more information, see **Section 26.1 "Configuration Bits"**). The Primary Oscillator Configuration bits, POSCMD<1:0> (FOSC<1:0>), and the Initial Oscillator Select Configuration bits, FNOSC<2:0> (FOSCSEL<2:0>), select the oscillator source that is used at a POR. The FRC Primary Oscillator with Postscaler (FRCDIV) is the default (unprogrammed) selection. The secondary oscillator, or one of the internal oscillators, may be chosen by programming these bit locations. The EC mode Frequency Range Configuration bits, POSCFREQ<1:0> (FOSC<4:3>), optimize power consumption when running in EC mode. The default configuration is "frequency range is greater than 8 MHz".

The Configuration bits allow users to choose between the various clock modes, shown in Table 9-1.

9.2.1 CLOCK SWITCHING MODE CONFIGURATION BITS

The FCKSMx Configuration bits (FOSC<7:6>) are used jointly to configure device clock switching and the FSCM. Clock switching is enabled only when FCKSM1 is programmed ('0'). The FSCM is enabled only when FCKSM<1:0> are both programmed ('00').

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	Notes
8 MHz FRC Oscillator with Postscaler (FRCDIV)	Internal	11	111	**1, 2**
500 kHz FRC Oscillator with Postscaler (LPFRCDIV)	Internal	11	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	11	101	**1**
Secondary (Timer1) Oscillator (SOSC)	Secondary	00	100	**1**
Primary Oscillator (HS) with PLL Module (HSPLL)	Primary	10	011	
Primary Oscillator (EC) with PLL Module (ECPLL)	Primary	00	011	
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	
8 MHz FRC Oscillator with PLL Module (FRCPLL)	Internal	11	001	**1**
8 MHz FRC Oscillator (FRC)	Internal	11	000	**1**

Note 1: The OSCO pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER 10-3: ULPWCON: ULPWU CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0
ULPEN	—	ULPSIDL	—	—	—	—	ULPSINK
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ULPEN:** ULPWU Module Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ULPSIDL:** ULPWU Stop in Idle Select bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **ULPSINK:** ULPWU Current Sink Enable bit
1 = Current sink is enabled
0 = Current sink is disabled

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R/W-0	R-0, HSC	R-1, HSC
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1, HSC	R-0, HSC	R-0, HSC	R/C-0, HS	R-0, HSC
URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
HS = Hardware Settable bit	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** UARTx Transmission Interrupt Mode Selection bits
- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register (TSR) and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** IrDA® Encoder Transmit Polarity Inversion bit

If IREN = 0:
- 1 = UxTX Idle '0'
- 0 = UxTX Idle '1'

If IREN = 1:
- 1 = UxTX Idle '1'
- 0 = UxTX Idle '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** UARTx Transmit Break bit
- 1 = Sends Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission is disabled or completed

bit 10 **UTXEN:** UARTx Transmit Enable bit
- 1 = Transmit is enabled; UxTX pin is controlled by UARTx
- 0 = Transmit is disabled; any pending transmission is aborted and the buffer is reset. UxTX pin is controlled by the PORT register.

bit 9 **UTXBF:** UARTx Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
- 1 = Transmit Shift Register is empty and the transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty; a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** UARTx Receive Interrupt Mode Selection bits
- 11 = Interrupt is set on a RSR transfer, making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on a RSR transfer, making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the RSR to the receive buffer; receive buffer has one or more characters.

FIGURE 19-2: ALARM MASK SETTINGS

Alarm Mask Setting (AMASK<3:0>)	Day of the Week	Month	Day	Hours	Minutes	Seconds
0000 - Every half second 0001 - Every second						
0010 - Every 10 seconds						s
0011 - Every minute						s s
0100 - Every 10 minutes					m	s s
0101 - Every hour					m m	s s
0110 - Every day				h h	m m	s s
0111 - Every week	d			h h	m m	s s
1000 - Every month			d d	h h	m m	s s
1001 - Every year(1)		m m	d d	h h	m m	s s

Note 1: Annually, except when configured for February 29.

19.5 POWER CONTROL

The RTCC includes a power control feature that allows the device to periodically wake-up an external device, wait for the device to be stable before sampling wake-up events from that device and then shut down the external device. This can be done completely autonomously by the RTCC, without the need to wake from the current low-power mode (Sleep, Deep Sleep, etc.).

To enable this feature, the RTCC must be enabled (RTCEN = 1), the PWCEN register bit must be set and the RTCC pin must be driving the PWC control signal (RTCOE = 1 and RTCOUT<1:0> = 11).

The polarity of the PWC control signal may be chosen using the PWCPOL register bit. Active-low or active-high may be used with the appropriate external switch to turn on or off the power to one or more external devices. The active-low setting may also be used in conjunction with an open-drain setting on the RTCC pin. This setting is able to drive the GND pin(s) of the external device directly (with the appropriate external V_{DD} pull-up device), without the need for external switches. Finally, the CHIME bit should be set to enable the PWC periodicity.

REGISTER 22-10: AD1CTMUENH: A/D CTMU ENABLE REGISTER (HIGH WORD)(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	CTMEN17	CTMEN16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as '0'.

bit 1-0 **CTMEN<17:16>:** CTMU Enabled During Conversion bits

1 = CTMU is enabled and connected to the selected channel during conversion
0 = CTMU is not connected to this channel

Note 1: Unimplemented channels are read as '0'.

REGISTER 22-11: AD1CTMUENL: A/D CTMU ENABLE REGISTER (LOW WORD)(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMEN15	CTMEN14	CTMEN13	CTMEN12	CTMUEN11	CTMEN10	CTMEN9	CTMEN8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMEN7	CTMEN6	CTMEN5	CTMEN4	CTMEN3	CTMEN2	CTMEN1	CTMEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **CTMEN<15:0>:** CTMU Enabled During Conversion bits

1 = CTMU is enabled and connected to the selected channel during conversion
0 = CTMU is not connected to this channel

Note 1: Unimplemented channels are read as '0'.

22.2 A/D Sampling Requirements

The analog input model of the 12-bit A/D Converter is shown in Figure 22-2. The total sampling time for the A/D is a function of the holding capacitor charge time.

For the A/D Converter to meet its specified accuracy, the Charge Holding Capacitor (CHOLD) must be allowed to fully charge to the voltage level on the analog input pin. The Source (RS) impedance, the Interconnect (RIC) impedance and the internal Sampling Switch (RSS) impedance combine to directly affect the time required to charge CHOLD. The combined impedance of the analog sources must, therefore, be small enough to fully charge the holding capacitor within the chosen sample time. To minimize the effects of pin leakage currents on the accuracy of the A/D Converter, the maximum recommended Source impedance, RS, is 2.5 kΩ. After the analog input channel is selected (changed), this sampling function must be completed prior to starting the conversion. The internal holding capacitor will be in a discharged state prior to each sample operation.

At least 1 TAD time period should be allowed between conversions for the sample time. For more details, see **Section 29.0 "Electrical Characteristics"**.

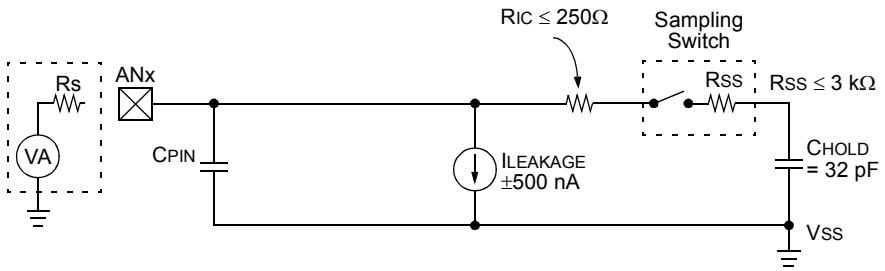
EQUATION 22-1: A/D CONVERSION CLOCK PERIOD

$$T_{AD} = T_{CY}(ADCS + 1)$$

$$ADCS = \frac{T_{AD}}{T_{CY}} - 1$$

Note: Based on TCY = 2/FOSC; Doze mode and PLL are disabled.

FIGURE 22-2: 12-BIT A/D CONVERTER ANALOG INPUT MODEL



Legend:		
	CPIN	= Input Capacitance
	VT	= Threshold Voltage
	ILEAKAGE	= Leakage Current at the Pin Due to Various Junctions
	RIC	= Interconnect Resistance
	RSS	= Sampling Switch Resistance
	CHOLD	= Sample-and-Hold Capacitance (from DAC)

Note: The CPIN value depends on the device package and is not tested. The effect of CPIN is negligible if Rs ≤ 5 kΩ.

NOTES:

25.3 Pulse Generation and Delay

The CTMU module can also generate an output pulse with edges that are not synchronous with the device's system clock. More specifically, it can generate a pulse with a programmable delay from an edge event input to the module.

When the module is configured for pulse generation delay by setting the TGEN bit (CTMUCON<12>), the internal current source is connected to the B input of Comparator 2. A capacitor (CDELAY) is connected to the Comparator 2 pin, C2INB, and the Comparator Voltage Reference, CVREF, is connected to C2INA. CVREF is then configured for a specific trip point. The module begins to charge CDELAY when an edge event is detected. While CVREF is greater than the voltage on CDELAY, CTPLS is high.

When the voltage on CDELAY equals CVREF, CTPLS goes low. With Comparator 2 configured as the second edge, this stops the CTMU from charging. In this state event, the CTMU automatically connects to ground. The IDISSEN bit doesn't need to be set and cleared before the next CTPLS cycle.

Figure 25-3 illustrates the external connections for pulse generation, as well as the relationship of the different analog modules required. While CTED1 is shown as the input pulse source, other options are available. A detailed discussion on pulse generation with the CTMU module is provided in the "*PIC24F Family Reference Manual*".

FIGURE 25-3: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR PULSE DELAY GENERATION

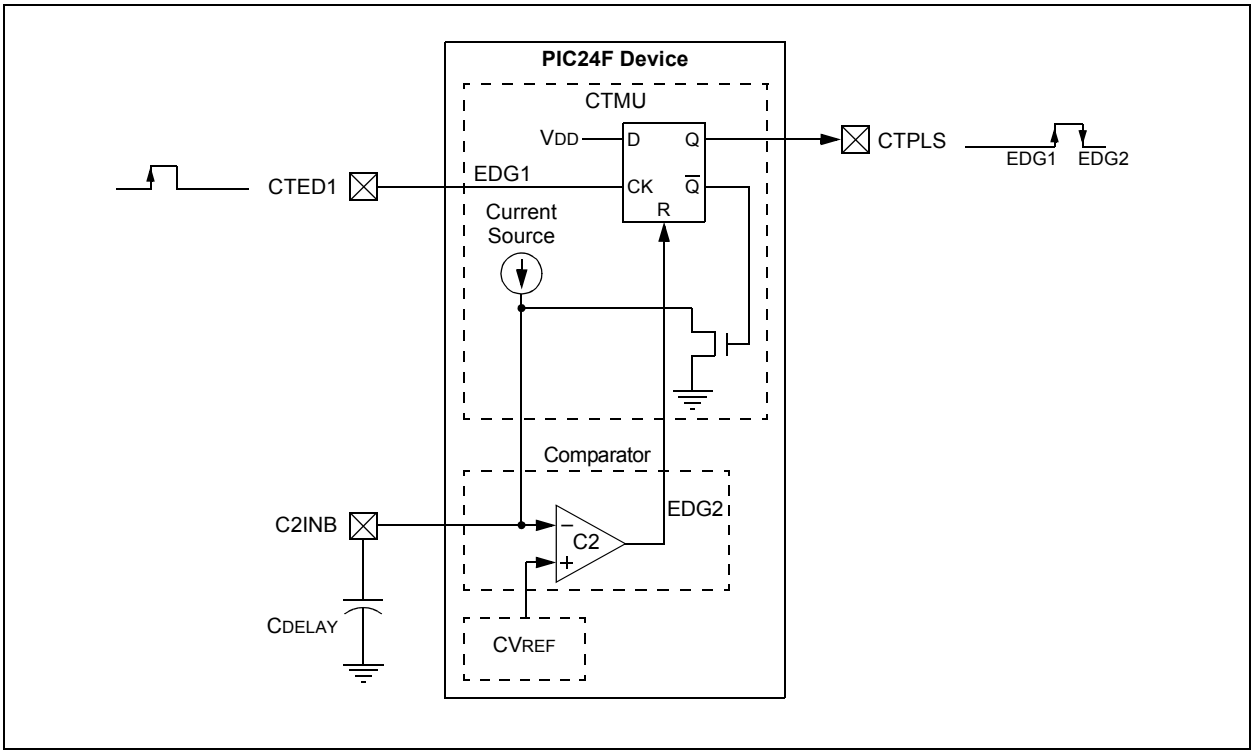


TABLE 29-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 29-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 20-Pin SPDIP	θ_{JA}	62.4	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SSOP	θ_{JA}	108	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SOIC	θ_{JA}	75	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	80.2	—	°C/W	**1**
Package Thermal Resistance, 28-Pin QFN	θ_{JA}	32	—	°C/W	**1**
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29	—	°C/W	**1**
Package Thermal Resistance, 48-Pin UQFN	θ_{JA}	—	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

TABLE 29-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX** **2.0V to 5.5V PIC24FV32KA3XX** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DC10	V_{DD}	**Supply Voltage**	1.8	—	3.6	V	For F devices
			2.0	—	5.5	V	For FV devices
DC12	V_{DR}	**RAM Data Retention Voltage(2)**	1.5	—	—	V	For F devices
			1.7	—	—	V	For FV devices
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	V_{SS}	—	0.7	V	
DC17	SV_{DD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 0.1s 0-2.5V in 60 ms

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This is the limit to which V_{DD} can be lowered without losing RAM data.

TABLE 29-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical**	**Max**	**Units**	**Conditions**	
Idle Current (IIDLE)						
DC40	PIC24FV32KA3XX	120	200	µA	2.0V	0.5 MIPS, FOSC = 1 MHz(1)
		160	430	µA	5.0V	
	PIC24F32KA3XX	50	100	µA	1.8V	
		90	370	µA	3.3V	
DC42	PIC24FV32KA3XX	165	—	µA	2.0V	1 MIPS, FOSC = 2 MHz(1)
		260	—	µA	5.0V	
	PIC24F32KA3XX	95	—	µA	1.8V	
		180	—	µA	3.3V	
DC44	PIC24FV32KA3XX	3.1	6.5	mA	5.0V	16 MIPS, FOSC = 32 MHz(1)
	PIC24F32KA3XX	2.9	6.0	mA	3.3V	
DC46	PIC24FV32KA3XX	0.65	—	mA	2.0V	FRC (4 MIPS), FOSC = 8 MHz
		1.0	—	mA	5.0V	
	PIC24F32KA3XX	0.55	—	mA	1.8V	
		1.0	—	mA	3.3V	
DC50	PIC24FV32KA3XX	60	200	µA	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
		70	350	µA	5.0V	
	PIC24F32KA3XX	2.2	18	µA	1.8V	
		4.0	60	µA	3.3V	

Legend: Unshaded rows represent PIC24F32KA3XX devices and shaded rows represent PIC24FV32KA3XX devices.

Note 1: Oscillator is in External Clock mode (FOSCSEL<2:0> = 010, FOSC<1:0> = 00).

FIGURE 30-7: TYPICAL AND MAXIMUM IDD vs. TEMPERATURE (FRC MODE)

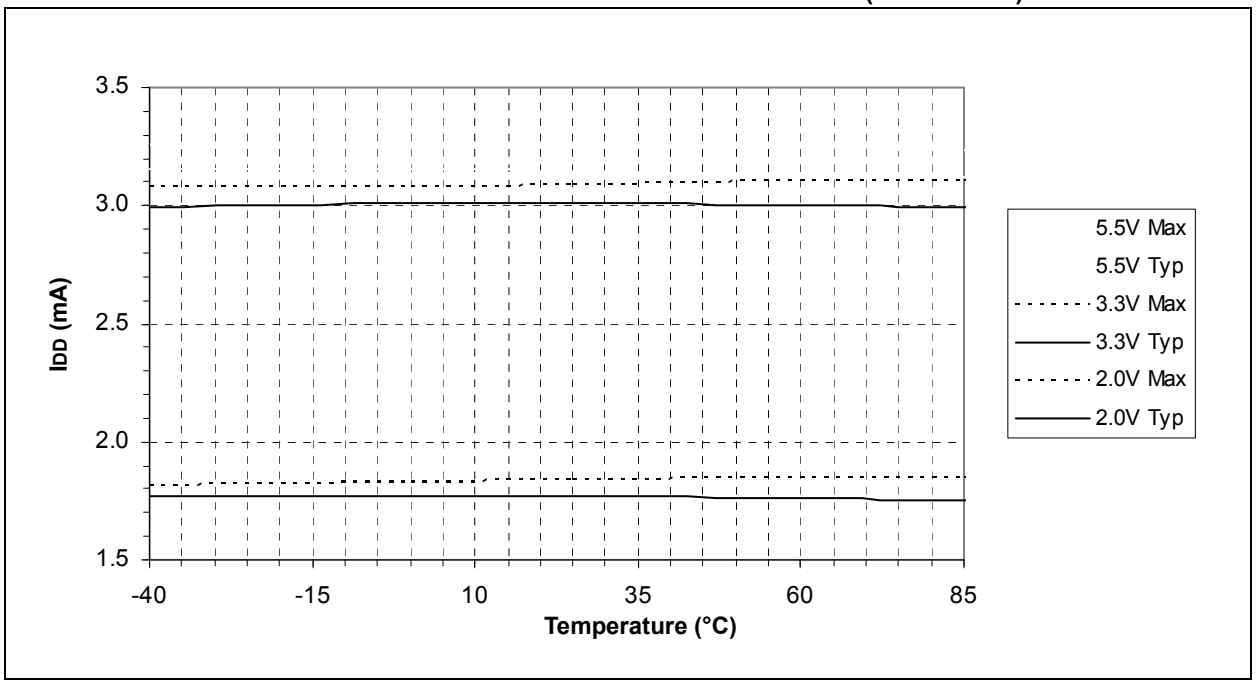
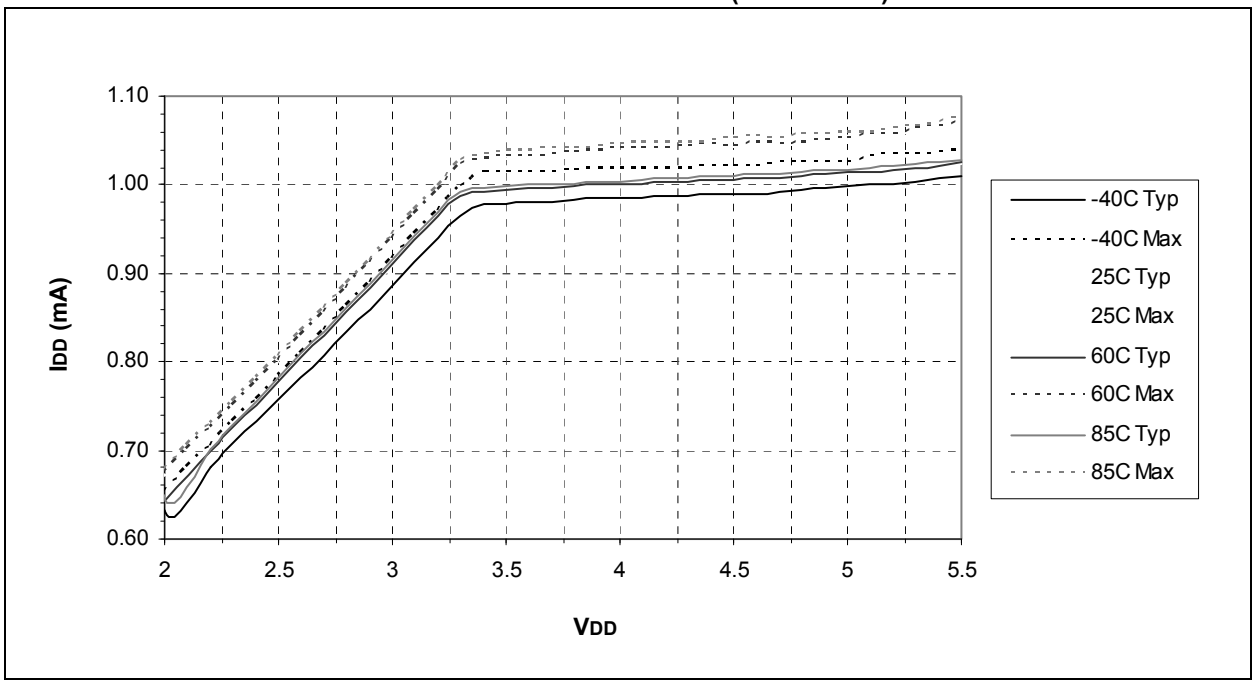
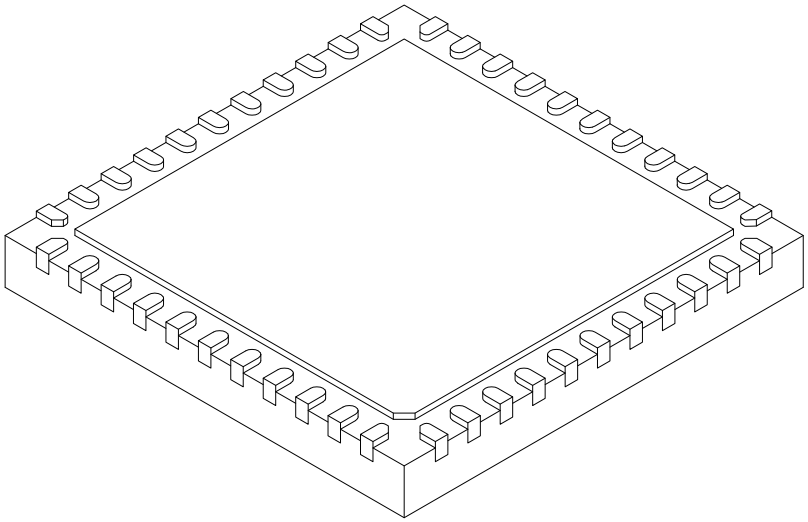


FIGURE 30-8: TYPICAL AND MAXIMUM IIDLE vs. VDD (FRC MODE)



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2